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(54) **Title**: CHEMICAL MECHANICAL PLANARIZATION PAD WITH VOID NETWORK

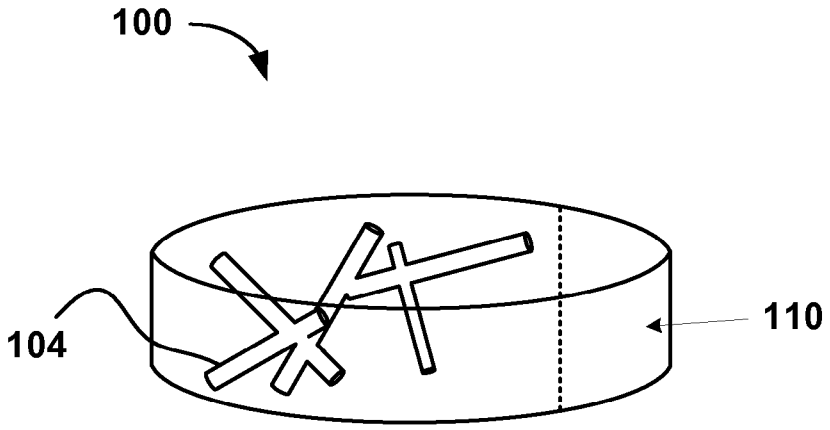


FIG. 1d

(57) **Abstract**: A polishing pad and a method of producing a polishing pad. The method includes providing a mold, having a first cavity and a second cavity, wherein the first cavity defines a recess, providing a polymer matrix material including void forming elements in the recess, forming a polishing pad and removing at least a portion of the elements from the polishing pad forming void spaces within the polishing pad by one of a chemical method or mechanical method, prior to use in chemical/mechanical planarization procedures.

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